

Material Content Data Sheet

RoHS

Sales Product Name	FF2600UXTR33T2M1	**Revision**	01
Issued	14.11.2024	**Weight***	705 g

Construction element	*Material group*	*CAS-Nr. if applicable*	*Materials*	*Average mass**	*Sum*	*Traces*	*Comment*
semiconductors	inorganic material	409-21-2	silicon-carbide	0,14%	0,15%		
	non noble metal	7429-90-5	aluminum			X	
	non noble metal	7440-02-0	nickel			X	
baseplate and substrate including metallisation	inorganic material	409-21-2	silicon-carbide	14,6%	37,2%		
	non noble metal	7429-90-5	aluminum	8,6%			
	non noble metal	7440-50-8	copper	5,4%			
	inorganic material	24304-00-5	aluminium nitride	4,3%			
	non noble metal	7440-31-5	tin	2,5%			
	noble metal	7440-22-4	silver	0,9%			
	non noble metal	7440-02-0	nickel	0,7%			
	non noble metal	7440-36-0	antimony	0,2%			
	inorganic material	7723-14-0	phosphorus			X	
bond wire	non noble metal	7440-50-8	copper	1,3%	1,3%		
	non noble metal	7429-90-5	aluminum			X	
silicone compounds	polymers	-	silicone-rubber PVMQ	10,1%	10,3%		
	inorganic material	-	other	0,1%			no duty of declaration
	polymers	-	silicone-rubber VMQ	0,1%			
housing and screws	polymers	-	polyamid	13,3%	22,2%		
	inorganic material	-	glass fiber	6,5%			
	inorganic material	-	flame retardant	1,6%			no duty of declaration
	non noble metal	7439-89-6	iron	0,4%			
	inorganic material	-	further additives	0,1%			no duty of declaration
	organic material	1333-86-4	carbon black	0,1%			
	non noble metal	7440-02-0	nickel			X	
	non noble metal	7440-47-3	chrome			X	
terminals	non noble metal	7440-50-8	copper	21,6%	28,7%		
	non noble metal	7439-89-6	iron	6,8%			
	non noble metal	7440-31-5	tin	0,1%			
	non noble metal	7440-02-0	nickel	0,1%		X	
	non noble metal	7440-66-6	zinc			X	
	inorganic material	7723-14-0	phosphorus			X	
SMD components	non noble metal	7439-89-6	iron		0,011%	X	
	non noble metal	7440-02-0	nickel			X	
	inorganic material	1317-36-8	lead monoxide	0,002%			RoHS compliant; according to exception 7c. I
	non noble metal	7440-50-8	copper			X	
	non noble metal	7440-31-5	tin			X	
*deviation	< 25%			Sum in total:	100%		

Important Remarks:

1. This document provides full declaration of all materials present in Infineon products above a threshold of 0,1 % b.w. (1000 ppm).
2. Trace concentrations (i.e. < 0,1 % b.w) present in products are marked with an "X" as far as they represent substances-of-concern.
   A list of substances-of-concern can be found at http://www.infineon.com/soc.
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